

Product Advisory (PA)

Subject: Datasheet specification change for listed Renesas ISL684x* Products

Publication Date: 7/24/2019

Effective Date: 7/24/2019

Revision Description:

Initial Release

Description of Change:

This notice is to inform you that Renesas Electronics America Inc has updated ISL684x* datasheet. The updates include changes to the following :

Page 7, Thermal Information

- Updated Theta JA (θ_{JA}) for DFN package changed from 77°C/W to 55°C/W.
- Updated Theta JC (θ_{JC}) for SOIC package changed from N/A to 60°C/W.

Affected Product List

ISL6840IBZ-T	ISL6842IBZ-T
ISL6840IRZ-T	ISL6843IBZ
ISL6840IUZ	ISL6843IBZ-T
ISL6840IUZ-T	ISL6843IUZ
ISL6842IBZ	ISL6843IUZ-T

Reason for Change:

The change aligns the datasheet with the product characteristics and is necessary to maintain product manufacturability in support of customer delivery requirements. The product datasheet is available at Renesas’s website at : -

<https://www.renesas.com/sg/en/www/doc/datasheet/isl6840-41-42-43-44.pdf>

Impact on fit, form, function, quality & reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

Product affected by this change is identifiable via Renesas’s internal traceability system.

Qualification status: Not Applicable

Sample availability: 7/24/2019

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
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